



Product Overview

Lead free no-clean wire solder that has been developed with a unique no clean flux system specifically for high temperature lead free alloys. Utilizing synthetically refined resin and a very effective activator, the solder wets and spreads beautifully. CS-PBF1 exhibits virtually no spattering and conforms to J-STD-004, RELO.

Features and Benefits

Exhibits virtually no spattering.

Lead-Free, RoHS Compliant.

No-Clean formula.

Technical Specifications

Solder Content Breakdown	96.5%Sn, 3.0%Ag, 0.5%Cu
Melting Range	422F-430F
Net Volume	11.0 Grams
Product Diameter	.032"
Harmonization Code:	8003.00.0000
RoHS Compliant	Yes
Safety Data Sheets	Download
Warranty Policy	Details